

AMENDMENTS TO THE CLAIMS

Please cancel claims 1 and 4 without prejudice or disclaimer of the underlying subject matter and amend claims 2 and 4-9 as set forth below.

1. (CANCELED)
2. (CURRENTLY AMENDED) A camera system ~~using~~having a camera module ~~comprising~~comprising:
a flexible substrate provided with a through-hole for light ~~transmission~~transmission;
an imaging element having a light receiving portion, an imaging element wherein
said imaging element is flip chip mounted on one a first side of the substrate such that the light
receiving portion is exposed through the through-holethrough-hole; and
a lens unit mounted on ~~the other~~a second side of the substrate so as to cover ~~the~~a
space over the light receiving portion of the imaging element.
3. (CANCELED)
4. (CURRENTLY AMENDED) The camera system of claim 2, wherein An the imaging
element havinghas on one side atthe light receiving portion on a first side and a shielding layer on
the other a second side opposite to the light receiving portion a shielding layerfirst side.
5. (CURRENTLY AMENDED) An imaging device ~~comprising~~comprising:
a ~~substrate~~substrate; and
an imaging element having ~~on one side~~ a light receiving portion on a first side, and a
shielding layer on a second side that is opposite the first side, wherein said imaging element is flip
chip mounted on the substrate such that said onefirst side is opposed to the substrate, and having a
shielding layer on the back surface of the element on the opposite side of the light receiving
portion.
6. (CURRENTLY AMENDED) An imaging device ~~comprising~~comprising:
a substrate having a through-hole for light ~~transmission~~transmission; and

an imaging element having ~~on one side~~ a light receiving ~~portion~~, portion on a first surface, wherein said imaging element is ~~flip chip mounted on said one side of the substrate such~~ that the light receiving portion is exposed through the ~~through hole~~, through-hole; and

a shielding layer on ~~the~~ a back surface of the imaging element, ~~on wherein said back surface is the opposite side of~~ opposite to the first surface of the imaging element having the light receiving portion.

7. (CURRENTLY AMENDED) ~~An~~ The imaging device according to Claim 5, wherein ~~there is provided~~ a black resin is applied to the periphery of the imaging element including ~~the~~ a connecting portion located between the substrate and the imaging element by the flip chip mounting ~~so as to cover the side surface and the back surface of the imaging element, and wherein a~~ part portion of the resin ~~constituting~~ is the shielding layer.

8. (CURRENTLY AMENDED) A camera module ~~comprising~~ comprising:
a substrate having a through-hole for light ~~transmission~~, transmission;
an imaging element having ~~on one side~~ a light receiving portion on a first surface of the imaging element and a shielding layer on a back surface of the imaging element, wherein said imaging element is flip chip mounted on ~~said one~~ a first side of the substrate such that the light receiving portion is exposed through the through-hole, ~~and a shielding layer on the back surface of the element on the opposite side of the light receiving portion, and a lens unit mounted on the other~~ a second side of the substrate.

9. (CURRENTLY AMENDED) A camera system using a camera module ~~comprising~~ comprising:
a substrate having a through-hole for light ~~transmission~~, transmission;
an imaging element having ~~on one side~~ a light receiving portion on a first surface of the imaging element and a shielding layer on a back surface of the imaging element, wherein said imaging element is flip chip mounted on ~~said one~~ a first side of the substrate such that the light receiving portion is exposed through the through-hole, ~~and a shielding layer on the back surface of~~

~~the element on the opposite side of the light receiving portion,~~ and a lens unit is mounted on the ~~other~~ a second side of the substrate.